

# Megasonic Wet Etching System

Wet Etching System can be used to etch wet anisotropic Si in bulk micromachining. Our system is designed simply and compactly. Especially the addition of the **MEGAONIC** holder can make the characteristics of Si etching be improved remarkably. Our system is adequate for the R&D and proto type production

## SPECIFICATIONS

- ▶ Wafer size : 4, 5, 6 inch
- ▶ Etching Solution : KOH, TMAH
- ▶ Megasonic Irradiation  
Power Range :  $\sim 30 \text{ W/cm}^2$
- ▶ Bath  
Etch Bath : PTFE  
Circulation Bath : PTFE
- ▶ Solution Temperature  
Max. Temp :  $100^\circ\text{C}$   
Temp Uniformity :  $\pm 1^\circ\text{C}$
- ▶ Etching Characteristics  
Etch Rate :  $\sim 1 \mu\text{m}/\text{min}$   
Etch Uniformity :  $\pm 2\%$   
Average Surface Roughness : less than  $70 \text{ nm}$   
( minimum :  $2 \text{ nm}$  )
- ▶ Solution Circulation : Teflon Circulation Pump
- ▶ Frame :  $850(\text{W})\text{mm} \times 750(\text{D})\text{mm} \times 800(\text{H})\text{mm}$

## APPLICATIONS

- ▶ Si Anisotropic Wet Etch
- ▶ PSL, Electroplating
- ▶ V-Groove, U-Groove, Cavity formation
- ▶ Membrane, microchannel formation

